

Technical Data
Data Sheet 3644, Rev. -

Surface Mount Device LED

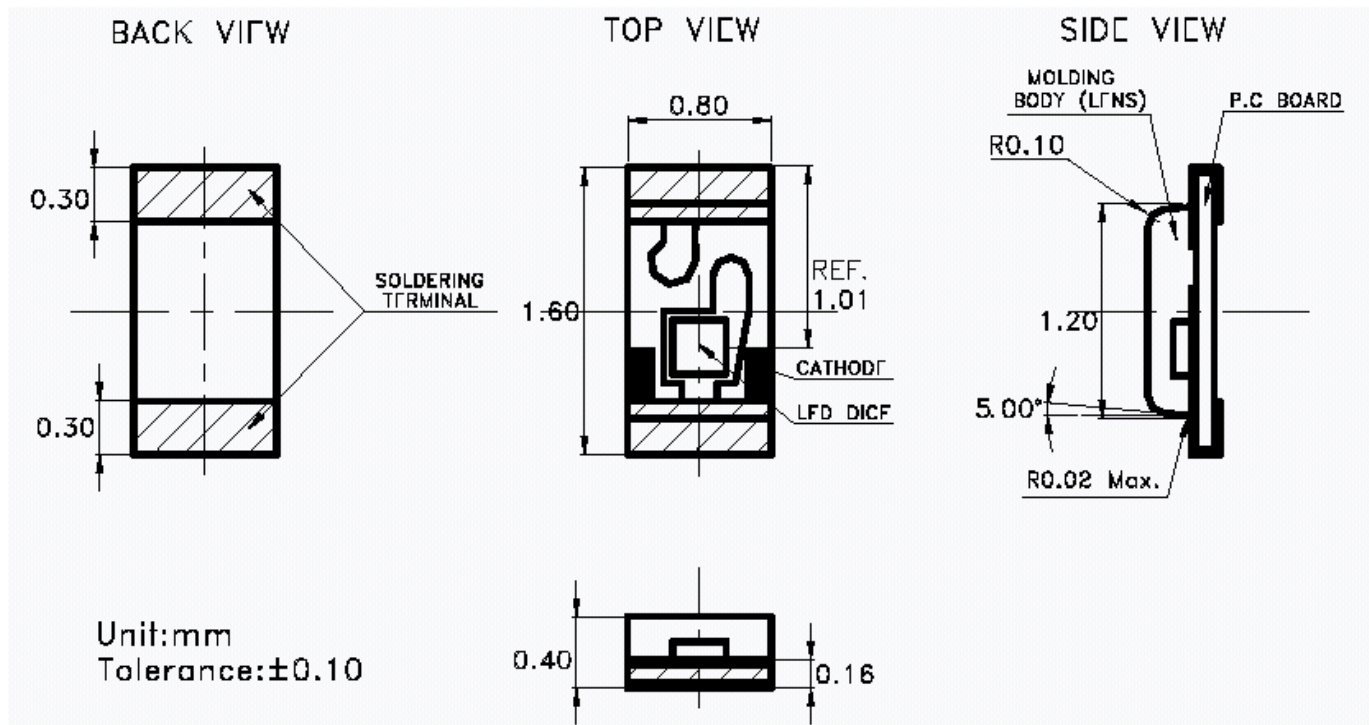
Features:

- Top view, wide view angle, single color chip LED.
- Compatible with automatic Pick & Place equipment.
- Compatible with Infrared and Wave soldering reflow solder processes.
- EIA STD package.

Ordering Information:

- Package in 8mm tape on 7" diameter reels.
- Tape quantity: 5000 pcs per reel with part number suffix "-T1"

Mechanical Dimensions: In mm



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm (.004") unless otherwise specified.

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Absolute Maximum Ratings (T_A = 25 °C)

Parameter	Symbol	Parameters	Unit
Power Dissipation	P _{AD}	100	mW
Peak Forward Current (1/10 Duty Cycle, f = 1kHz)	I _{PF}	100	mA
Continuous Forward Current	I _{AF}	25	mA
Reverse Voltage	V _R	5	V
Derating Linearly from 25 °C	-	0.25	mA/°C
Electrostatic Discharge Threshold(HBM) ^{Note A}	ESD	150	V
Operating Temperature Range	T _{opr}	-40 ~ +85	°C
Storage Temperature Range	T _{stg}	-40 ~ +85	°C
Wave Soldering Condition (Two times Max)	-	260 (for 5 seconds)	°C
Infrared Soldering Condition (Two times Max)	-	240 (for 5 seconds)	°C

Note A:

HBM: Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

Electro-Optical Characteristic (T_A = 25 °C)

Parameter	Symbol	Parameters	Unit
Chip Material	-	InGaN	-
Light Color	-	Blue	-
Lens Color	-	Water Clear	-
Luminous Intensity @I _F = 20 mA	I _v	40.0 (Typ.) 25.0 (Min)	mcd
Viewing Angle Typical @I _F = 20 mA	2θ _{1/2}	130	Degree
Peak Emission Wavelength	λ _p	468	nm
Dominant Wavelength @I _F = 20 mA	λ _D	470	nm
Spectral Line Half-Width @I _F = 20 mA	Δλ	25	nm
Forward Voltage @I _F = 20 mA	V _F	3.8 (Max) 3.3 (Typ.)	V
Max. Reverse Current @ 5V	I _R	50	μA

TECHNICAL DATA

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